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WHAT IS CLAIMED IS:

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1. A semiconductor device substrate, comprising:  
a substrate body having a wiring layer;  
a base formed by a material that is different  
from a material of said substrate body, supporting said  
10 substrate body, and having an opening forming portion  
where a semiconductor element is mounted; and  
a reinforcing member larger than the opening  
forming portion, provided in said substrate body at a  
portion corresponding to the opening forming portion, and  
15 reinforcing said substrate body at the portion  
corresponding to the opening forming portion.
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2. The semiconductor device substrate as claimed  
in claim 1, wherein the reinforcing member is a circuit  
board having a capacitor part that electrically connects  
the semiconductor element and the wiring layer.
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3. The semiconductor device substrate as claimed  
30 in claim 2, wherein the reinforcing member is arranged on  
the base via an abutting member made of a metal.

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4. The semiconductor device substrate as claimed  
in claim 1, wherein the reinforcing member is an  
5 interposer having a via that directly electrically  
connects the semiconductor element and the wiring layer.

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5. The semiconductor device substrate as claimed  
in claim 4, wherein the reinforcing member is arranged on  
the base via an abutting member made of a metal.

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6. The semiconductor device substrate as claimed  
in claim 1, wherein the reinforcing member is arranged on  
20 the base via an abutting member made of a metal.

25 7. A manufacturing method of a substrate, said  
manufacturing method comprising the steps of:  
manufacturing a reinforcing member;  
arranging the reinforcing member on a base at a  
portion corresponding to an opening forming portion of the  
30 base;

forming a substrate body on the base on which  
the reinforcing member is arranged, said substrate body  
including a wiring layer and made of a material that is

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different from a material of the base; and

forming the opening forming portion smaller than the reinforcing member, thereby exposing a part of the reinforcing member at the opening forming portion.

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8. The manufacturing method as claimed in claim 7, wherein the step of manufacturing the reinforcing member includes a step of forming a capacitor on a core member.

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9. The manufacturing method as claimed in claim 8, wherein the step of manufacturing the reinforcing member includes a step of forming a via penetrating the core member.

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10. The manufacturing method as claimed in claim 9, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

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11. The manufacturing method as claimed in claim 8, wherein the reinforcing member is arranged on the base via an abutting member made of a metal.

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5           12. The manufacturing method as claimed in claim  
7, wherein the reinforcing member is arranged on the base  
via an abutting member made of a metal.

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          13. A semiconductor device, comprising:  
          the semiconductor device substrate as claimed in  
claim 1; and  
15           a semiconductor element mounted in the opening  
forming portion of the semiconductor device substrate.

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          14. A semiconductor device, comprising:  
          the semiconductor device substrate as claimed in  
claim 2; and  
          a semiconductor element mounted in the opening  
25       forming portion of the semiconductor device substrate.

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          15. A semiconductor device, comprising:  
          the semiconductor device substrate as claimed in  
claim 3; and  
          a semiconductor element mounted in the opening

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forming portion of the semiconductor device substrate.

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16. A semiconductor device, comprising:

the semiconductor device substrate as claimed in  
claim 4; and

a semiconductor element mounted in the opening  
10 forming portion of the semiconductor device substrate.

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17. A semiconductor device, comprising:

the semiconductor device substrate as claimed in  
claim 5; and

a semiconductor element mounted in the opening  
forming portion of the semiconductor device substrate.

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18. A semiconductor device, comprising:

25 the semiconductor device substrate as claimed in  
claim 6; and

a semiconductor element mounted in the opening  
forming portion of the semiconductor device substrate.